#### 1.8mm TRI-LEVEL LED INDICATOR

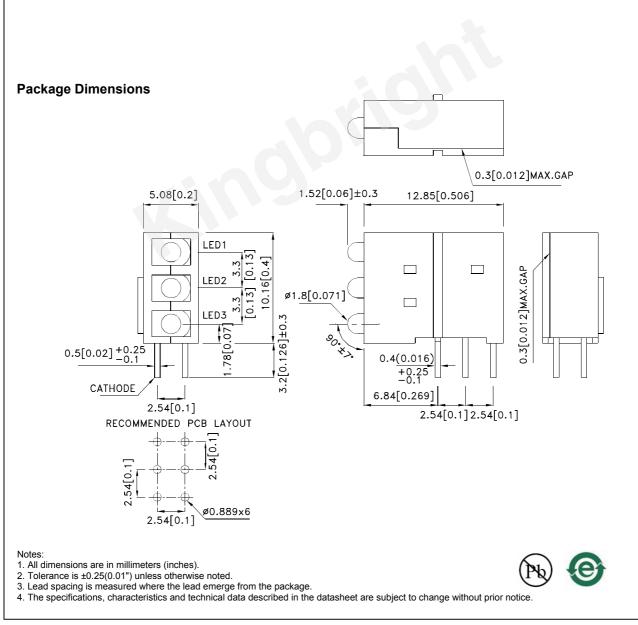
Part Number: L-4060XHA/3GD Green

### Features

- Pre-trimmed leads for pc mounting.
- Black case enhances contrast ratio.
- High reliability life measured in years.
- Housing UL rating:94V-0.
- Housing material: type 66 nylon.
- RoHS compliant.

#### Description

The Green source color devices are made with Gallium Phosphide Green Light Emitting Diode.



SPEC NO: DSAO1163 APPROVED: WYNEC REV NO: V.1B CHECKED: Allen Liu DATE: JAN/15/2015 DRAWN: Q.M.Chen PAGE: 1 OF 5 ERP: 1102015470

#### **Selection Guide**

Part No.	Dice	Lens Type	lv (mo @ 10	/	Viewing Angle [1]
			Min.	Тур.	201/2
L-4060XHA/3GD	Green (GaP)	Green Diffused	6	12	70°

Notes

θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
Luminous intensity/ luminous Flux: +/-15%.

3. Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

#### Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Green	565		nm	I⊧=20mA
λD [1]	Dominant Wavelength	Green	568		nm	I⊧=20mA
Δλ1/2	Spectral Line Half-width	Green	30		nm	I⊧=20mA
С	Capacitance	Green	15		pF	VF=0V;f=1MHz
Vf [2]	Forward Voltage	Green	2.2	2.5	V	I⊧=20mA
lr	Reverse Current	Green		10	uA	VR = 5V

Notes: 1. Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V. 3. Wavelength value is traceable to the CIE127-2007 compliant national standards.

4. Excess driving current and/or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

#### Absolute Maximum Ratings at TA=25°C

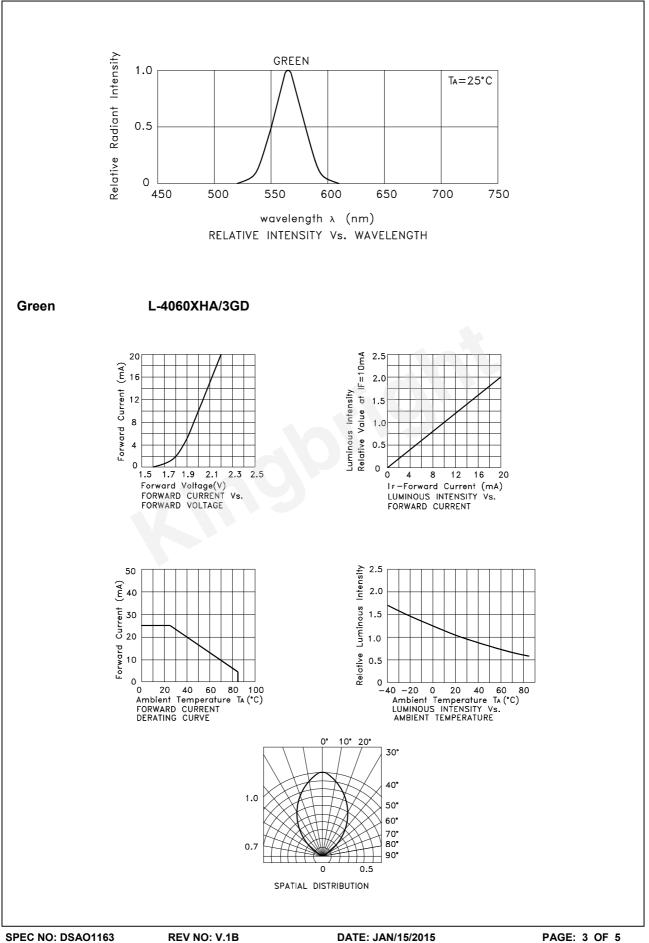
Parameter	Green	Units	
Power dissipation	62.5	mW	
DC Forward Current	25	mA	
Peak Forward Current [1]	140	mA	
Reverse Voltage	5	V	
Operating/Storage Temperature	-40°C To +85°C		
Lead Solder Temperature [2]	260°C For 3 Seconds		
Lead Solder Temperature [3]	260°C For 5 Seconds		

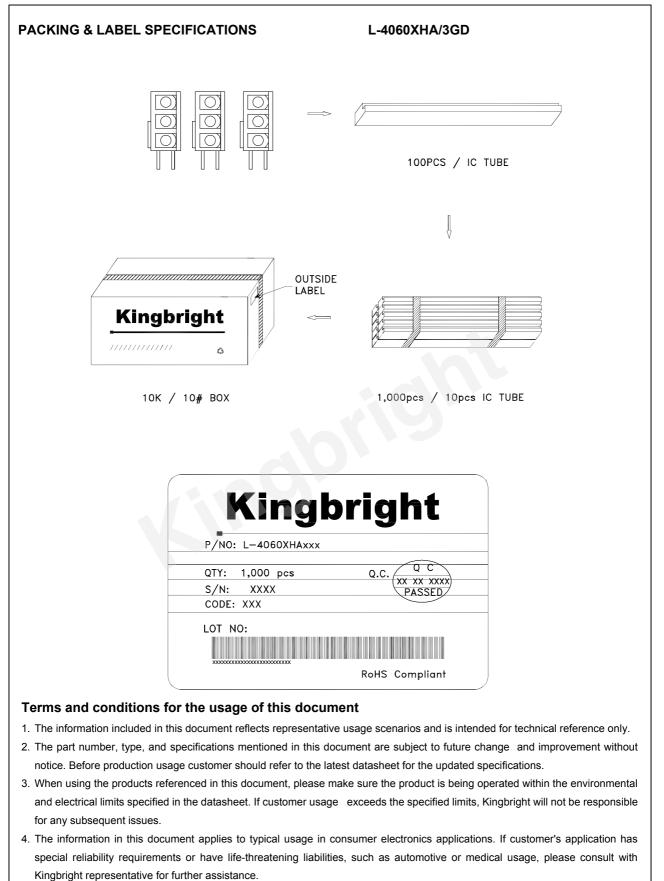
Notes:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

2. 2mm below package base.

3. 5mm below package base.





- 5. The contents and information of this document may not be reproduced or re-transmitted without permission by Kingbright.
- 6. All design applications should refer to Kingbright application notes available at <a href="http://www.kingbright.com/application\_notes">http://www.kingbright.com/application\_notes</a>

DATE: JAN/15/2015 DRAWN: Q.M.Chen

#### PRECAUTIONS

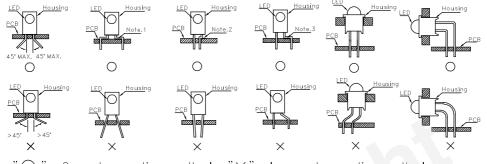
1. Storage conditions:

a.Avoid continued exposure to the condensing moisture environment and keep the product away from rapid transitions in ambient temperature.

b.LEDs should be stored with temperature  $\leq$  30°C and relative humidity <60%.

c.Product in the original sealed package is recommended to be assembled within 72 hours of opening. Product in opened package for more than a week should be baked for 30 (+10/-0) hours at 85 ~ 100°C.

2. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures.

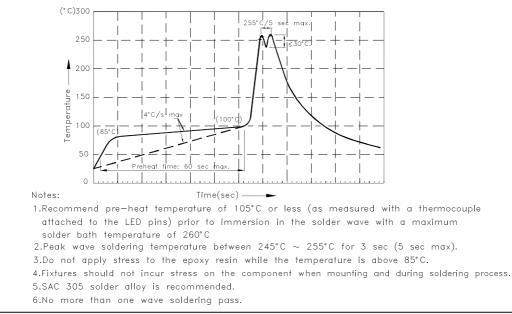


"○" Correct mounting method "X" Incorrect mounting method Note 1-3: Do not route PCB trace in the contact area between the leadframe and the PCB to prevent short-circuits.

3. During soldering, component covers and holders should leave clearance to avoid placing damaging stress on the LED during soldering.



- 4. The tip of the soldering iron should never touch the lens epoxy.
- 5. Through-hole LEDs are incompatible with reflow soldering.
- 6. If the LED will undergo multiple soldering passes or face other processes where the part may be subjected to intense heat, please check with Kingbright for compatibility.
- 7. Recommended Wave Soldering Profiles:



SPEC NO: DSAO1163 APPROVED: WYNEC REV NO: V.1B CHECKED: Allen Liu DATE: JAN/15/2015 DRAWN: Q.M.Chen PAGE: 5 OF 5 ERP: 1102015470